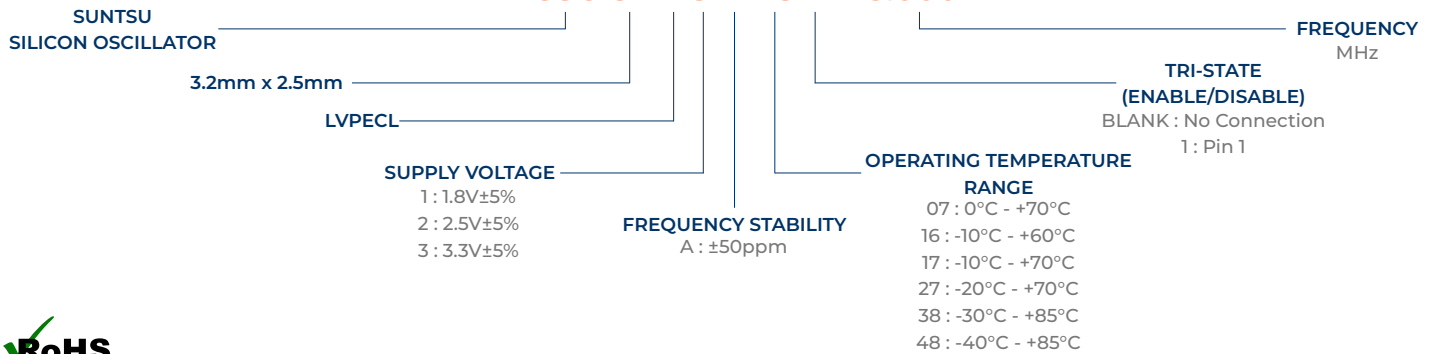


- | Features |
|--|
| • ± 50 ppm (Frequency Stability) Available |
| • All Silicon without Quartz and MEMS |
| • LVPECL Output |
| • Low Jitter |
| • Built in LDO and Power Filter Circuit |
| • Moisture Sensitivity Level 2 |

- | Applications |
|---------------------------|
| • Intelligent Terminal |
| • Ethernet |
| • Consumer Electronics |
| • Communication Equipment |

Part Numbering Guide

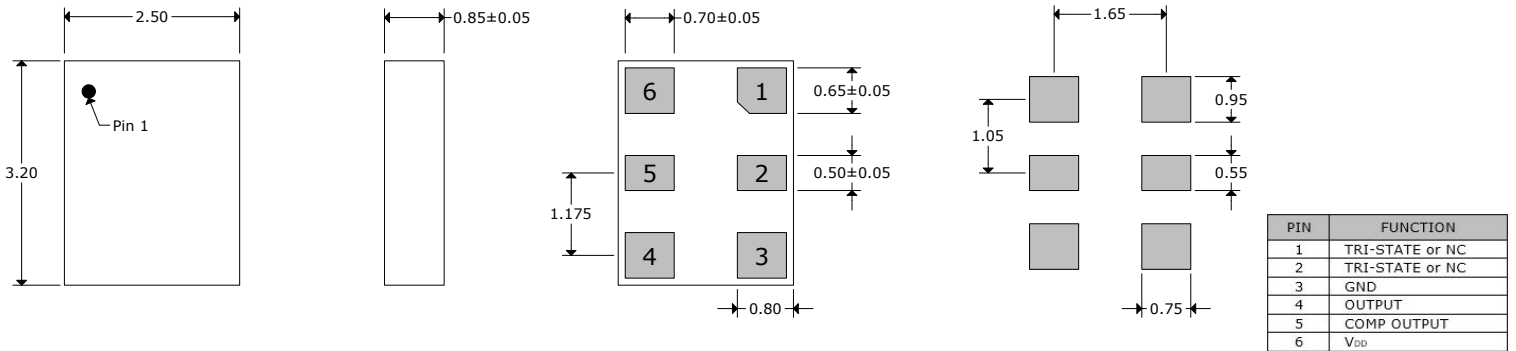
SSO 32 P 3 A 48 1 - 25.000M



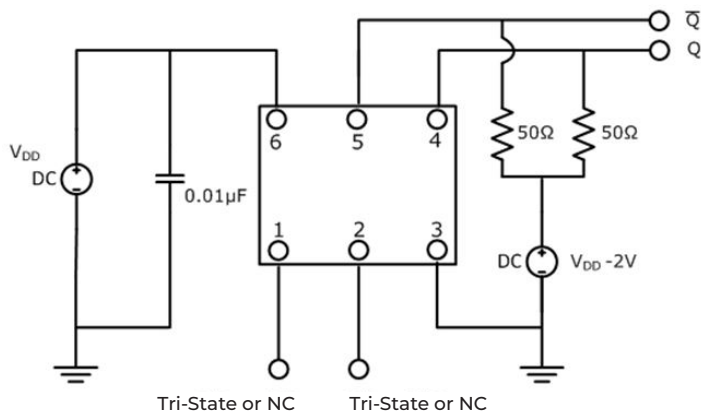
Electrical Parameters	Units	Minimum	Typical	Maximum	Remarks
Frequency Range	MHz	0.01		350	
Frequency Stability (Includes Initial Tolerance at 25°C, Frequency Stability over Operating Temperature, Output Load Change, Supply Voltage Change, and Ten Years Aging at 25°C.)	ppm	-50		50	
Operating Temperature	°C	-40		85	See part numbering guide for options
Storage Temperature	°C	-55		105	
Supply Voltage (V _{DD}) - 1.8V option	V	1.71	1.8	1.89	
Supply Voltage (V _{DD}) - 2.5V option	V	2.375	2.5	2.625	
Supply Voltage (V _{DD}) - 3.3V option	V	3.135	3.3	3.47	
Current (I _{DD}) - 1.8V to 3.3V	mA		60	70	
Output Load (LVPECL)	Ω			50	50 Ω into V _{DD} -2.0V _{DC}
Common Mode Voltage of Diff. Output (V _{OC})	V	V _{DD} -1.55		V _{DD} -1.25	
Differential Output Voltage (V _{OD})	V _{PP}	1.4		1.85	
Rise (TR) and Fall (TF) Time	ps			350	
Symmetry (Duty Cycle)	%	45	50	55	
Tri-State Input Voltage - Enable	V	0.7*V _{DD}			No Connection
Tri-State Input Voltage - Disable	V			0.3*V _{DD}	
Start-Up Time	ms			4	
Phase Jitter (12kHz ~ 20MHz)	fs		350	750	

Outline Drawing & Land Pattern

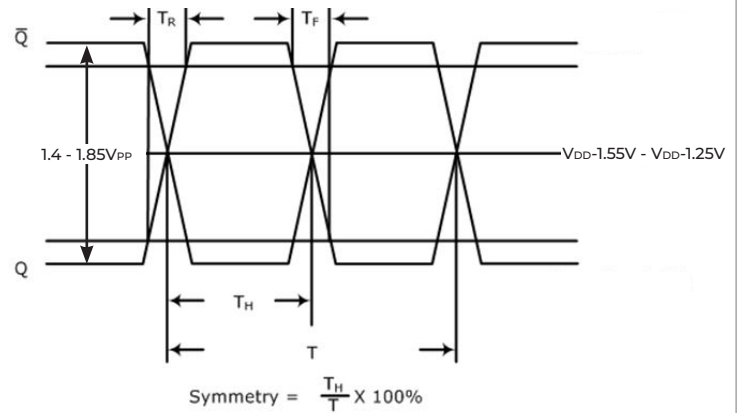
All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.



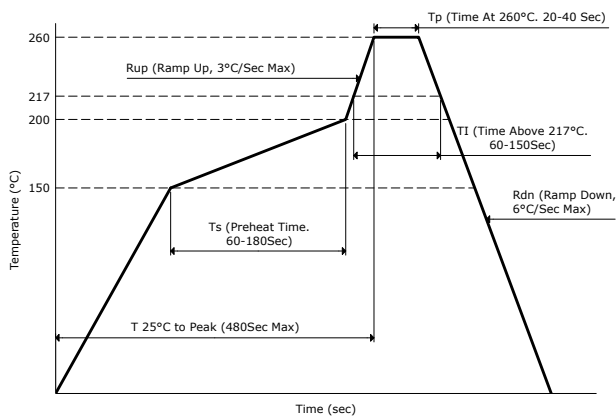
Test Circuit (LVPECL)



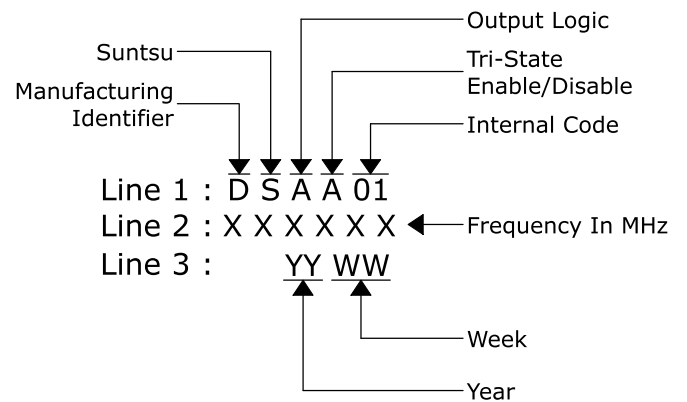
Waveform (LVPECL)



Reflow Profile



Part Marking



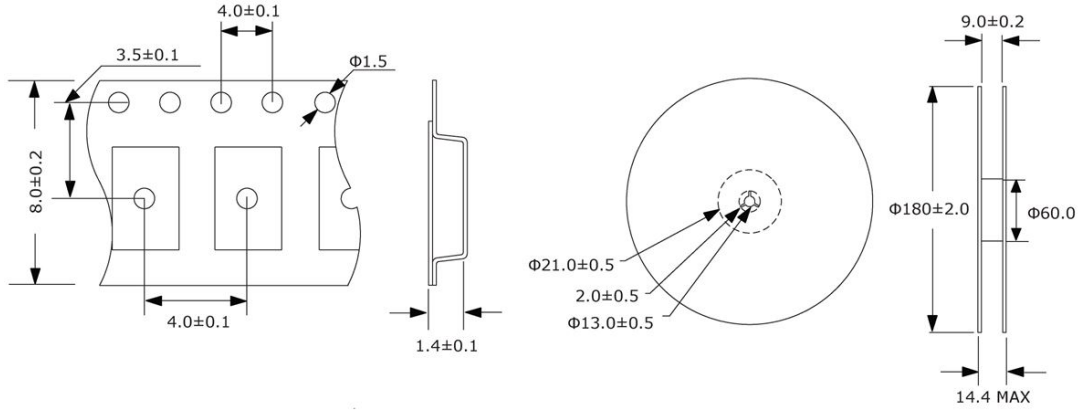
Six Character Frequency Info

MXXXXX	<1MHz
XMXXXX	≥1MHz; <10MHz
XXMXXX	≥10MHz; <100MHz
XXXMXX	≥100MHz; <350MHz

Tape And Reel Dimensions

All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.

3,000pcs/Reel



Environmental Specifications

Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Solderability	MIL-STD-883, Method 2003
Moisture Sensitivity	J-STD-020, MSL 2

Mechanical Specifications

Mechanical Shock	MIL-STD-202, Method 213, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Resistance to Solvents	MIL-STD-202, Method 215
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K